Electronic Acknowledgement Receipt				
EFS ID:	3967066			
Application Number:	10537509			
International Application Number:				
Confirmation Number:	4531			
Title of Invention:	Method for cutting semiconductor substrate			
First Named Inventor/Applicant Name:	Fumitsugu Fukuyo			
Customer Number:	23973			
Filer:	Joseph John Buczynski/Towanna Bolling			
Filer Authorized By:	Joseph John Buczynski			
Attorney Docket Number:	46884-5388 (211285)			
Receipt Date:	18-SEP-2008			
Filing Date:	30-NOV-2005			
Time Stamp:	16:36:53			
Application Type:	U.S. National Stage under 35 USC 371			

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1		45004 5300 :4.2 -45	89429		_
	46884_5388_ids2.pdf	d33be75a24415aa15271bcc9fcef345fd165 396e	yes	3	
	Multip	part Description/PDF files in	zip description		
	Document Description		Start	End	
	Information Disclosure Statement Letter		1	2	
	Information Disclosure Statement (IDS) Filed (SB/08)		3	3	
Warnings:					
Information:					
2	2 NPL Documents	46884_5388_searchrpt.pdf	75673	no	3
2 WE Documents	40004_9900_9carcimpapar	9398cfbe3d977d7a067cc03907732edfe502 6a1f			
Warnings:					
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3	3 Foreign Reference	46884_5388_ep1580800ref.pdf	1364615	no	41
			5c5f8f8e03ec84f604f70a6015b8fce87ccde 984		
Warnings:					
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4 Foreign Reference	46884_5388_ep1498216ref.pdf	1142873	no	35	
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Warnings:					
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5	5 Fee Worksheet (PTO-06)	fee-info.pdf	30359	no	2
5 Fee Worksheet (F10-00)	1ee-11110.pu1	b35e9619bfe2c952f635076e52918e539ea5 9fc9			
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